



3-Terminal 1A Positive Voltage Regulator

CL7812DT



TO-252 (DPAK)
Surface Mount Package
RoHS compliant

TO-252 (DPAK)

GENERAL DESCRIPTION:

The CL7812DT series of three terminal positive regulators are available in the TO-252(DPAK) package and with several fixed output voltages, making them useful in a wide range of applications. Each type employs internal current limiting, thermal shut down and safe operating area protection, making it essentially indestructible. If adequate heat sinking is provided, they can deliver over 1.0A output current. Although designed primarily as fixed voltage regulators, these devices can be used with external components to obtain adjustable voltages and currents.

ABSOLUTE MAXIMUM RATINGS (T_a = 25 °C)

Parameter	Symbol	Тур	Unit
Input Voltage	V _I	19	V
Output Voltage	Vo	12	V
Peak Current	I _{PK}	1.7	Α
Operating Temperature Range	T_{OPR}	0~125	°C
Storage Temperature Rang	T_{STG}	-65~150	°C



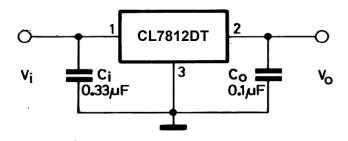


ELECTRICAL CHARACTERISTICS ($T_a = 25 \, ^{\circ}C$)

(Refer to test circuit, $I_o = 500 \text{mA}$, $V_i = 19 \text{V}$, $C_i = 0.33 \text{uF}$, $C_o = 0.1 \text{uF}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Output Voltage	Vo	$T_j = 25^{\circ}C, V_l = 15V - 27V,$ $I_O = 5.0 \text{ mA} - 1.0 \text{A}$	11.5	12	12.5	V
Line Regulation	$\triangle V_{o}$	$T_i = 25^{\circ}\text{C}, V_i = 15\text{V} - 30\text{V}$ $T_i = 25^{\circ}\text{C}, V_i = 16\text{V} \text{ to } 22\text{V}$		-	240 120	mV
Load Regulation	$\triangle V_{o}$	$T_i = 25$ °C, $I_O = 5.0$ mA to 1.0A $T_j = 25$ °C, $I_O = 250$ mA to 750mA	-	-	240 120	mV
Quiescent Current	I _Q	T _J = 25 °C	-	-	8	mA
Quiescent Current Change	$\triangle I_Q$	$I_o = 5.0$ mA to 1.0A $T_i = 25$ °C, $V_i = 15$ V to 25V	-	-	0.5 1	mA mA
Output Voltage Drift	$\triangle V_o / \triangle T$	I _o = 5.0mA	-	-1	-	mV/°C
Ripple Rejection	R_R	f = 120Hz, V _O = 15V to 25V	56	80	-	dB
Dropout Voltage	V_{Drop}	I _O = 1.0A, T _J = 25 °C	-	2	-	V
Output Resistance	R _o	f = 1KHz	-	0.02	-	Ohm
Short Circuit Current	I _{sc}	V _I = 35V, T _A = 25 °C	-	300	-	mA
Peak Current	I _{PK}	T _J = 25 °C	-	-	1.7	Α

Test Circuit







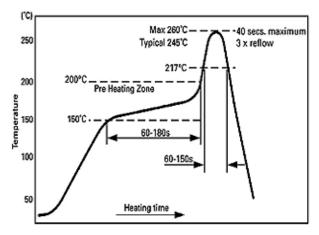
Recommended Reflow Solder Profiles

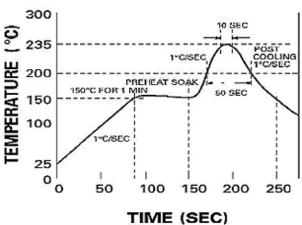
The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1 Figure 2





Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat – Temperature Range – Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds
Time maintained above: – Temperature – Time	200°C 30-50 seconds	217°C 60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.

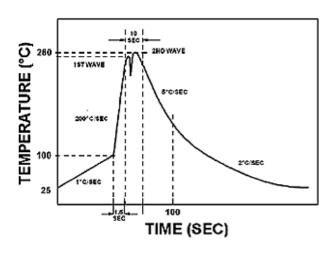


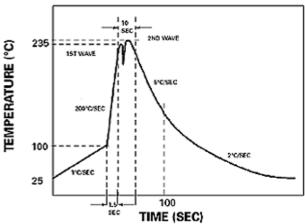


Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





Wave Profiles in Tabular Form

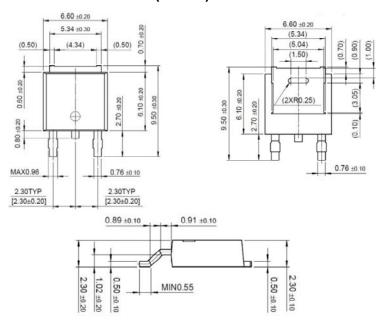
Profile Feature	Sn-Pb System	Pb-free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max.





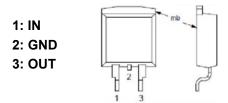
PACKAGE DETAILS

TO-252 (DPAK)

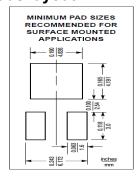


All dimensions are in mm

Pin configuration



PCB pads layout:







Recommended Product Storage Environment for Discrete **Semiconductor Devices**

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- · The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level		
Level	Time	Condition
1	Unlimited	≤30 °C / 85% RH
2	1 Year	≤30 °C / 60% RH
2a	4 Weeks	≤30 °C / 60% RH
3	168 Hours	≤30 °C / 60% RH
4	72 Hours	≤30 °C / 60% RH
5	48 Hours	≤30 °C / 60% RH
5a	24 Hours	≤30 °C / 60% RH
6	Time on Label(TOL)	≤30 °C / 60% RH





Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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